



SHEET 1 OF 1

Substitute for forms 449A/PTO & 1449B/PTO		ATTORNEY'S DKT NO. 024445-349	APPLICATION NO. 10/606,963
INFORMATION DISCLOSURE STATEMENT BY APPLICANT			
APPLICANT Torbjörn JOELSSON et al.		FILING DATE June 27, 2003	
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U.S. PATENT DOCUMENTS				
Examiner Initials	Document Number	Kind Code (if known)	Name of Patentee or Applicant of Cited Document	Issue/Publication Date (MM-DD-YYYY)
AJ	5,208,102		SCHULZ et al.	05-04-1993
	5,330,853		HOFMANN et al.	07-19-1994
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Examiner Initials	Document Number	Kind Code (if known)	Country	Date of Publication (MM-DD-YYYY)	Translation Yes No
AJ	0 448 720	B1	EP	07-05-1995	X

NON PATENT LITERATURE DOCUMENTS	
Examiner Initials	Include name of author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.
AJ	W. Jeltschko und H. Nowotny, DIE KRISTALLSTRUKTUR von Ti_3SiC_2 - ein neuer KOMPLEXCARBID-TYP, Monatsh für Chem. Vol. 98 pp. 329-337 (1967)
	J. J. Nickl et al., GASPHASENABSCHIEDUNG IM SYSTEM TI-SI-C, Journal of the Less-Common Metals Vol. 26 pp 335-353 (1972)
	T. Goto et al., CHEMICALLY VAPOR DEPOSITED Ti_3SiC_2 , Mat. Res. Bull., Vol. 22 pp. 1195-1201 (1987)
	T. Seppänen et al., STRUCTURAL CHARACTERIZATION OF EPITAXIAL Ti_3SiC_2 FILMS, Proceedings Scandinavian Society for Electron Microscopy June 12-15-2002, pp. 142-143
AJ	M. W. Barsoum, THE $M_{n+1}AX_n$ PHASES: A NEW CLASS OF SOLIDS; THERMODYNAMICALLY STABLE NANOLAMINATES, Prog. Solid St. Chem. Vol. 28 pp. 201-228 (2000)

Examiner Signature		Date Considered	5/05
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